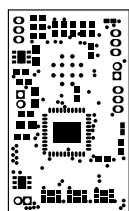
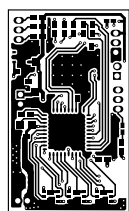


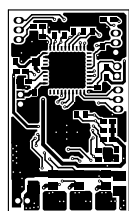
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01587		
PLOT NAME = Top Overlay	GENERATED : 2/13/2018 6:03:41 PM	TEXAS INSTRUMENTS	



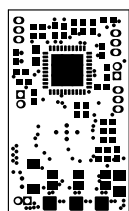
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01587		
PLOT NAME = Top Solder Mask	GENERATED : 2/13/2018 6:03:42 PM	TEXAS INSTRUMENTS	



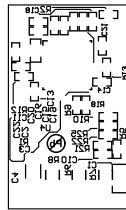
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01587		
PLOT NAME = Top Layer	GENERATED : 2/13/2018 6:03:43 PM	TEXAS INSTRUMENTS	



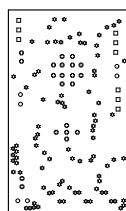
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01587		
PLOT NAME = Bottom Layer	GENERATED : 2/13/2018 6:03:44 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01587		
PLOT NAME = Bottom Solder Mask	GENERATED : 2/13/2018 6:03:45 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01587		
PLOT NAME = Bottom Overlay	GENERATED : 2/13/2018 6:03:46 PM	TEXAS INSTRUMENTS	

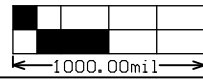
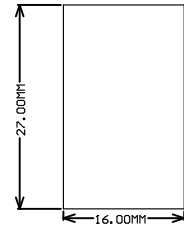


Symbol	Count	Hole Size	Plated	Hole Type	Via/Pad
⊕	21	7.87mil (0.200mm)	PTH	Round	Via
☆	88	8.00mil (0.203mm)	PTH	Round	Via
□	9	27.56mil (0.700mm)	PTH	Round	Pad
○	6	28.00mil (0.711mm)	PTH	Round	Pad
	124 Total				

Tolerance:

For 7.874mil +0/-7.874mil  
 For 8mil +0/-8mil  
 For PTH Drill +/-3mil

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01587		
PLOT NAME = Drill Drawing	GENERATED : 2/13/2018 6:03:47 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01587	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01587		
PLOT NAME = Board Dimensions	GENERATED : 2/13/2018 6:03:48 PM	TEXAS INSTRUMENTS	



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